# T-Fusion: Thermal Prediction of 3D ICs with Multi-fidelity Fusion

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# BACKGROUND AND PREVIOUS WORK

# METHODOLOGY

# EXPERIMENT RESULTS

# **SUMMARY**

## **Motivation: Why care about Thermal Modelling**

Moore's Law is slowing down

3D Integration offers a solution

But brings thermal challenges:

- Higher power density
- Complex heat paths
- Performance degradation



#### Need fast and accurate thermal analysis

# **SOTA** and limitation

#### **Traditional Methods: numerical solvers**

- COMSOL (1000 + seconds)
- Hotspot (1450 + seconds )
- MTA ( 200 + seconds )

#### **ML-based Methods: learn the mapping**

- Deep OHeat (100 + hours training)
- ThermPINN (2D only)
- Therm-Transformer (large data needed)





#### Need fast and accurate thermal prediction with limited data

# Insights

## **Multi-fidelity Approach**

- High-fidelity: Accurate but expensive
- Low-fidelity: Fast but less accurate
- Fusion: Best of both worlds



#### Leverage both Low- and High-Fidelity as data source

# Challenge:

## **Key requirements**

- Large-scale temperature fields
- Different resolutions across different fidelities
- Spatial correlation
- Temporal consistency
- Small training dataset
- Scalability

## **T-Fusion Model**

#### Key innovation:

#### **Tensor based cross fidelity transformation**

- Preserve spatial relationship
- Resolution alignment
- Reducing computation from O(d<sup>3</sup>) to O(d<sup>2</sup>)

#### **Efficient Training**

- $L = L' + L^r$
- Reduce memory

## **Experimental Results: Benchmark**

#### **Test Cases of 3D ICs**

- single-core
- quad-core
- eight-core chips

#### Input:

Power consumption for each function block

#### **Output:**

Spatial-temporal temperature profile

#### **Experiment platform**

Intel Xeon CPU @ 2.40GHz NVIDIA A100 PCIe 40GB GPU 128 DDR-4 memory



#### **Example Power Differences in Three 3D-ICs**

## **Vs. Single Fidelity Steady-State Prediction**

Steady-state temperature prediction against SOTA STGP with only high-fidelity data

based on a given certain computational time (for generating training data)

Table 2. The Wesh Office Configurations							
	fidelity	mesh scale(mm)	DOF	runtime			
Single-Core	low	3.3-24	151706	14s			
	high	0.12-1.2	11749552	1272s			
Quad-Core	low	3.3-24	142513	23s			
	high	0.12-1.2	13087276	1092s			
Octa-Core	low	3.3-24	105152	15s			
	high	0.1-1	15956118	1276s			

#### **Table 2: The Mesh Grid Configurations**



Improvement:

- Training cost:
  3 × reduction
- Model Training Time:
  5 × faster
- Model Inference Time:
  5 × improvement

## **Vs. SOTA ML Model and Numerical Tools**

Table 3: Steady Temperature Comparisons of T-Fusion, GP and DeepOHeat(SOTA)									
		High Fidelity Training Sets	$R^2$	MAPE(%)	PAPE(%)	Training Time	Mean Predict Time		
DeepOHeat[8]	/	50 in each iteration (10000 iterations)	/	0.16	1.00	100 h	0.1s		
T-Fusion	Single-Core	15	0.98	0.21	0.26	132.05s	0.0016s		
	Quad-Core	15	0.90	0.52	0.33	184.87s	0.0015s		
	Octa-Core	15	0.97	0.31	0.54	66.91s	0.0015s		
GP	Single-Core	30	0.74	0.40	0.19	40.26s	0.0003s		
	Quad-Core	30	0.66	0.95	1.24	35.98s	0.0004s		
	Octa-Core	30	0.89	0.62	0.63	15.23s	0.0008s		

#### Vs. DeepOHeat

- Training cost:
  3 × reduction
- Model Training Time:
  5 × faster
- Model Inference Time:
  5 × improvement

#### **Vs. commercial numerical simulation**

Acceleration: 100,000x -1,000,00x; Error: <1K

Table 4: runtime and Maximum temperature comparisonsamong COMSOL, MTA, Hotspot and T-Fusion on Single-Core

	Max(K)	Error(K)	Predict Time(s)	Speedup
<b>T-Fusion</b>	349.91	-1.03	0.0015	/
COMSOL	350.94	/	1249	1,000,000x
Hotspot	353.37	+2.43	1450.6	1,000,000x
MTA	350.944	+0.04	217	100,000x

## **I** Transient Temperature Field Prediction



## **Transient Temperature Field Prediction**

Visualization of the cross-section with the largest thermal gradient in the entire 3D chip structure.



#### **Observation:**

with drastic temperature changes, low-fidelity data introduces greater errors compared to high-fidelity data

The chip temperature diffusion trends from time step 1 to time step 10 and a comparison between T-Fusion model predictions and the ground truth.

# Summary and Future work

## **Key Contributions:**

- Novel multi-fidelity fusion approach for thermal field prediction
- Up to 10,000 × reduction in training data (vs. single fidelity ML model)
- Up to **1,000,000** × speedup (vs. numerical solvers)
- Consistently <1K error (Vs. Comsol)</li>
- Effective for both **steady-state** and **transient** analysis

## **Future Directions:**

- Extension to more complex 3D architectures
- Integration with design optimization tools
- Real-time thermal monitoring applications

# Thank you for your attention and engagement

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Codes and more multi-fidelity models and optimization can be downloaded at:

https://github.com/IceLab-X/FidelityFusion/

